

ADHESIVE FILM FOR WAFER TREATMENT

ABSTRACT

An adhesive film for a wafer treatment of the present disclosure includes a multilayer base including an upper base layer and a lower base layer, a first adhesive layer disposed on a top face of the upper base layer, and a second adhesive layer disposed between the upper base layer and the lower base layer, and a tensile strength of the adhesive film is in a range of 70 to 150 MPa. The adhesive film has excellent machineability by reducing or eliminating stress (shear stress) generated during a back face grinding process so as to prevent damage to the wafer, suppressing curl, and preventing a movement or a collision and cracking of segmented semiconductor chips.

<FIG. 1>